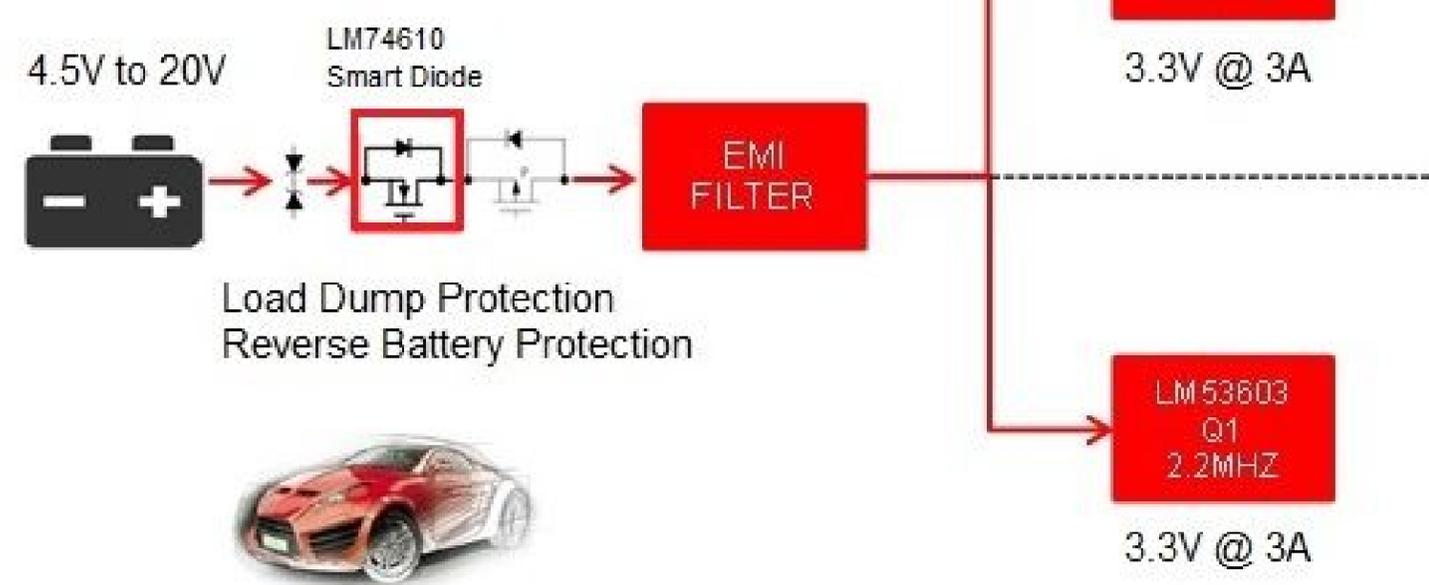
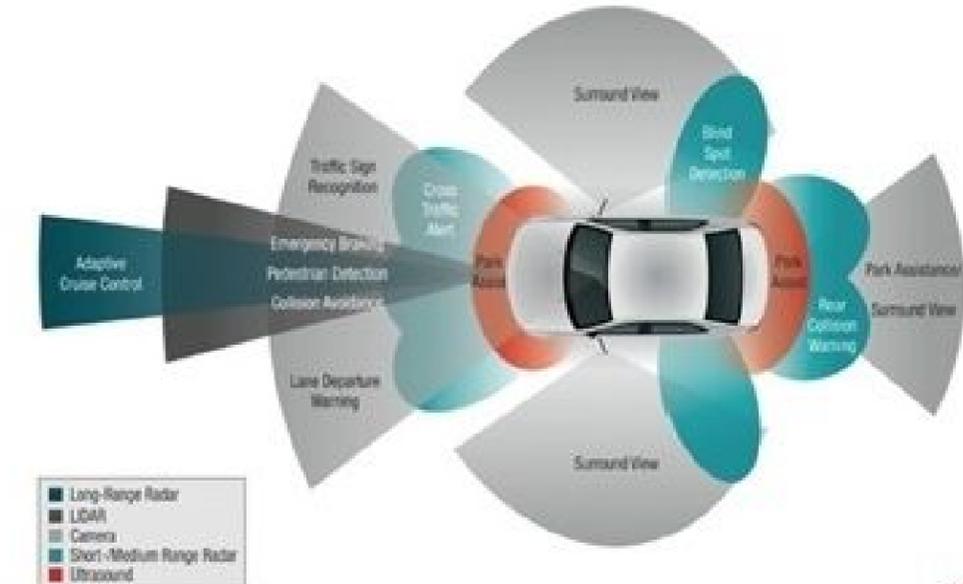
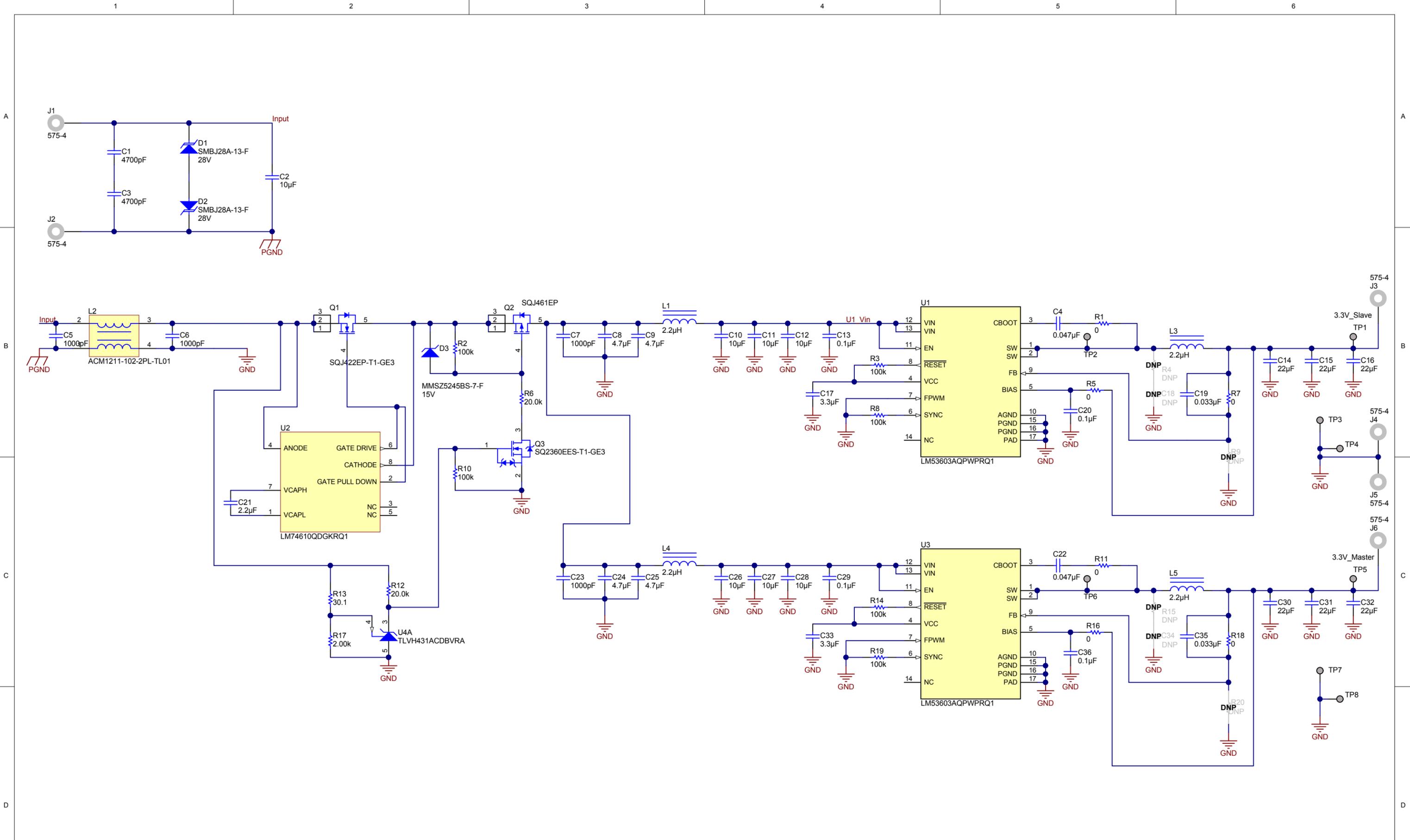


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable: N/A	Designed for: Public Release	Mod. Date: 9/28/2015	
TID #: PMP10750	Project Title: SMPS for ADAS System	Sheet: 1 of 3	
Number: PMP10750	Rev: E1	File: PMP10750_CoverSheet.SchDoc	Size: B
SVN Rev: Version control disabled	Drawn By: Michael DeSando	Engineer: Michael DeSando	http://www.ti.com © Texas Instruments 2015



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Orderable: N/A	Designed for: Public Release	Mod. Date: 9/28/2015
TID #: PMP10750	Project Title: SMPS for ADAS System	
Number: PMP10750	Rev: E1	Sheet Title:
Drawn By: Michael DeSando	File: PMP10750_Schematic.SchDoc	Assembly Variant: 001
Engineer: Michael DeSando	Contact: http://www.ti.com/support	Sheet: 2 of 3
		Size: B



H1 NY PMS 440 0025 PH
 H2 NY PMS 440 0025 PH
 H3 NY PMS 440 0025 PH
 H4 NY PMS 440 0025 PH

H5 1902C
 H6 1902C
 H7 1902C
 H8 1902C

H9 SJ-5303 (CLEAR)
 H10 SJ-5303 (CLEAR)
 H11 SJ-5303 (CLEAR)
 H12 SJ-5303 (CLEAR)

DNP FID1
 DNP FID2
 DNP FID3

PCB Number: PMP10750
 PCB Rev: E1

PCB LOGO
 Texas Instruments

PCB LOGO
 Pb-Free Symbol

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Assembly Note
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: PMP10750	Project Title: SMPS for ADAS System		
Number: PMP10750	Rev: E1	Sheet: 3 of 3	
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By: Michael DeSando	File: PMP10750_TID_Hardware.SchDoc	Contact: http://www.ti.com/support	

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